

PROCEEDINGS OF SPIE

Metrology, Inspection, and Process Control XXXIX

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Editors

24–28 February 2025

San Jose, California, United States

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Published by

SPIE

Volume 13426

Part One of Two Parts

Proceedings of SPIE 0277-786X, V. 13426

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

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Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in *Metrology, Inspection, and Process Control XXXIX*, edited by Matthew J. Sendelbach, Nivea G. Schuch, Proc. of SPIE 13426, Seven-digit Article CID Number (DD/MM/YYYY); (DOI URL).

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510686380

ISBN: 9781510686397 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time)

SPIE.org

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Contents

xiii Conference Committee

Part One

KEYNOTES

- 13426 03 **Evolution of in-fab e-beam inspection technology and its role in the future (from 2D to 4D) (Keynote Paper)** [13426-1]
- 13426 04 **3D metrology and inspection to enable the rise of stacked transistors, wafers, and chips (Keynote Paper)** [13426-2]

OPTICAL METROLOGY

- 13426 05 **Full-wafer 3D metrology solution based on imaging ellipsometry for process uniformity control** [13426-3]
- 13426 06 **Critical in-line OCD metrology for CFET manufacturing** [13426-4]
- 13426 07 **Optimized EUV scatterometry measurements with tunable high harmonic generation and the Fisher information matrix** [13426-5]
- 13426 08 **Phase retrieval of periodic patterns** [13426-6]
- 13426 09 **Ellipsometry in the EUV regime** [13426-8]

ELECTRON BEAM METROLOGY

- 13426 0A **On-product, on-device overlay breakdown by layer and contributor using a high-voltage scanning electron microscope** [13426-10]
- 13426 0B **Beyond 3σ : roughness metrology evolution at the last 20 years (in memory of Ben Bunday)** [13426-11]
- 13426 0C **True metrology with reduced resist shrinkage effect for process window optimization and EUV stochastic effects analysis** [13426-12]
- 13426 0D **LER distribution measurement using HHCF-based noise correction** [13426-13]

- 13426 OE **Enhancing overlay metrology accuracy via E-beam simulation and SEM target optimization** [13426-246]
- 13426 OF **Contribution of optical overlay target design to non-zero offset stability** [13426-210]
- 13426 OG **GenAI applications of vision-language models for semiconductor defect classification** [13426-213]

OVERLAY AND EPE

- 13426 OH **Small angle x-ray scattering industrial overlay metrology solutions for 7nm nodes and beyond** [13426-14]
- 13426 OI **Optimization toward non-zero offset stability in overlay control: trends and prospects** [13426-15]
- 13426 OJ **Budget analysis on dual layer edge placement error in logic devices** [13426-16]
- 13426 OK **A grid mapping-based U-net algorithm for photolithography overlay virtual metrology** [13426-17]

METROLOGY AND INSPECTION FOR THE EUV ERA

- 13426 OL **E-beam metrology for high-NA: revisiting the imec protocol** [13426-18]
- 13426 OM **Foundation deep learning model for accurate SEM image segmentation for CD-SEM measurements** [13426-95]
- 13426 ON **Via to line-end contact failures: the role of stochastics** [13426-20]
- 13426 OO **Efficient way of reducing contaminant induced by interactions between EUV photoresist and electron beam in CD-SEM: the route to carryover free SEM metrology** [13426-21]
- 13426 OP **Extreme-ultraviolet-lithography line-space patterning defect detection using voltage contrast SEM** [13426-22]

MACHINE LEARNING AND ARTIFICIAL INTELLIGENCE

- 13426 OQ **A virtual defect metrology system utilizing photolithography scanner topography maps to quantitatively detect gross defects, perform in-line yield prediction, and identify defect generating tools (Invited Paper)** [13426-23]
- 13426 OR **Enhancing critical dimension measurement with nanometer scale using CNNs and optical theory-derived 3D point spread function** [13426-24]

- 13426 OT **Optimizing surface reconstruction using a segmented scanning electron microscope detector and deep learning (Karel Urbanek Best Student Paper Award)** [13426-26]
- 13426 OU **Cherry-picking: automated model term selection for precise overlay and CD process control** [13426-27]
- 13426 OV **Detection limits of AI-based SEM dimensional metrology** [13426-28]
- 13426 OW **Machine learning and edge placement error improve electron beam inspection capture rate** [13426-102]

3D PROFILE AND SHAPE METROLOGY

- 13426 OX **Atomic force microscopy: from research lab to high-volume manufacturing (Invited Paper)** [13426-29]
- 13426 OY **Hybrid metrology for non-destructive lateral cavity etch measurements of 8-superlattice layer nanowire test structures (NWTs) using optical Mueller matrix spectroscopic ellipsometry (MMSE), x-ray diffraction (XRD), and x-ray reflectivity (XRR)** [13426-30]
- 13426 OZ **An open-source CD-SAXS library framework for parallelized calculations to facilitate the modeling and uncertainty calculations of complex material stacks** [13426-31]
- 13426 IO **Multi-technique reference measurement of critical dimension and shape for model validation in scanning electron microscopy** [13426-32]
- 13426 II **Metrology-design co-optimization for BEOL dimensional characterization using scatterometry** [13426-33]

METROLOGY AND INSPECTION FOR ADVANCED MEMORY

- 13426 I2 **3D-DRAM Si/SiGe superlattices: inspection strategies and evaluation (Invited Paper)** [13426-34]
- 13426 I3 **High-speed e-beam metrology using a pattern recognition-based image enhancement method** [13426-35]
- 13426 I4 **The deep learning technology for predicting memory hole contact distortion profile with multiple in-line data in 3D NAND flash memory** [13426-36]
- 13426 I5 **Zernike-based photolithography track modules matching for wafer CDU** [13426-37]
- 13426 I6 **Physical plasma information-enhanced structure prediction in semiconductors using optical emission spectroscopy during etching process** [13426-38]

MATERIALS CHARACTERIZATION AND METROLOGY

13426 19 **Advanced packaging raw materials assurance by characterization** [13426-41]

13426 1A **Predicting and measuring scummed contact holes** [13426-83]

METROLOGY FOR ADVANCED LOGIC

13426 1C **Estimating crystal heights of GAA device from 2D SEM images (Invited Paper)** [13426-44]

13426 1D **Emerging x-ray metrology techniques with evolving front-end-of-line high-technology IC nodes** [13426-45]

13426 1E **Scatterometry-informed machine learning study to determine bi-directional intercorrelation of adjacent patterning steps** [13426-46]

13426 1G **Inline x-ray metrology for complementary field-effect transistors (CFET)** [13426-48]

INSPECTION

13426 1H **High-NA EUV defectivity inspection: overview and challenges (Invited Paper)** [13426-49]

13426 1I **Surface pre-charging for mitigating imaging issues in multibeam SEM-based semiconductor device defect inspection** [13426-50]

13426 1J **Multibeam inspection applications development for advanced logic device nodes** [13426-51]

13426 1L **Semiconductor image analysis using data-efficient machine learning** [13426-53]

HETEROGENEOUS INTEGRATION AND ADVANCED PACKAGING

13426 1M **Suitability of half-wavelength contact acoustic microscopy to detect deeply buried voids** [13426-54]

13426 1N **Cu pad height evaluation technique using four-directional BSE signal of SEM for hybrid bonding applications** [13426-55]

13426 1O **Through glass via detection and inspection by holographic optical metrology** [13426-56]

13426 1P **Challenges and responses of metrology technologies for the new wave of 3D NAND devices** [13426-57]

NOVEL METHODS

- 13426 1R **Nondestructive in-cell conductivity metrology for memory semiconductors using near-field THz spectroscopy** [13426-59]
- 13426 1T **Development of an inspection method for electrical leakage tailored to target defect** [13426-61]
- 13426 1U **Leveraging AI and ML to transform Twinscan into an inline macro defect inspection system** [13426-62]
- 13426 1V **Lab-based multi-wavelength EUV diffractometry for critical dimension metrology** [13426-63]

LATE BREAKING NEWS

- 13426 1X **Using programmed defect vehicle to understand printability of defect/2D structures and characterize it through EUV process impact** [13426-65]
- 13426 1Y **Self-calibration overlay on ribbon-FET SRAM-like targets using full Mueller broadband spectroscopic ellipsometry for advanced process control** [13426-66]
- 13426 1Z **The sub-ppm level of stochastic failure model for random logic design** [13426-67]
- 13426 20 **Fast joint in-device metrology of overlay and tilt of multi-tier 3DNAND devices** [13426-149]

POSTER SESSION

- 13426 22 **A comparison of generative AI models for the top-down SEM image of line and space patterns** [13426-70]
- 13426 23 **DRAM capacitor-to-capacitor short process characterization via large field of view SEM metrology analysis** [13426-71]
- 13426 26 **Advanced pattern contour extraction function for see-through BSE images of high voltage SEM** [13426-75]
- 13426 27 **Define a measurement standard to monitor local variabilities of immersion lithography baseline for photonic devices** [13426-76]

Part Two

- 13426 28 **Toward extreme throughput nanotopography metrology with atomic force microscope arrays** [13426-77]
- 13426 29 **Innovative approach for roughness characterization of arbitrary polygons** [13426-78]
- 13426 2A **Prediction of electrical characteristics using spectrum and metrological data based on deep learning model** [13426-79]
- 13426 2B **FIB/SEM for inline 3D metrology and defect analysis** [13426-81]
- 13426 2C **Die-to-prompt: visual language model-based defect inspection and anomaly detection** [13426-82]
- 13426 2D **High-performing virtual metrology with group-wise feature transformation and advanced data aggregation techniques** [13426-84]
- 13426 2E **Spectral reflectometry for process monitoring in high aspect ratio TSV fabrication to improve uniformity** [13426-85]
- 13426 2F **Holistic EPE measurement and qualification by large field of view (LFOV) contour-based metrology** [13426-86]
- 13426 2H **First roughness measurement of SOG/SOC core pattern in depth direction with novel 3D roughness measurement techniques** [13426-89]
- 13426 2I **Reference-less defect inspection method based on unsupervised deep learning for semiconductors** [13426-90]
- 13426 2J **3D reconstruction of 3D NAND memory etch profiles using FIB-SEM: identifying variances in etched hole patterns** [13426-91]
- 13426 2K **Dual-camera imaging overlay metrology on center of symmetry for on-product overlay stability** [13426-92]
- 13426 2L **Full-chip voltage contrast inference using deep learning You Only Look Once: Voltage Contrast (YOLO-VC)** [13426-93]
- 13426 2M **Accurate process window determination for EUV lithography using large field of view eBeam metrology and stochastic-aware modeling** [13426-94]
- 13426 2N **Metrology and segmentation in SEM/TEM imaging: accelerating semiconductor analysis through advanced deep learning techniques** [13426-96]
- 13426 2O **A novel machine learning solution to maximize defective die capture and yield prediction accuracy in inline process control with e-beam inspection** [13426-97]
- 13426 2P **Optimization of defect detection sensitivity and cost of ownership reduction in nano imprint lithography through design for inspection and advanced optical inspection** [13426-98]

- 13426 2Q **Subsurface scanning probe microscopy for reference overlay metrology** [13426-99]
- 13426 2R **Non-destructive sub-nanometer evaluation of sidewall coverage in deep holes by small-angle x-ray scattering** [13426-100]
- 13426 2S **SiliconBASE: multi-task baseline model for semiconductor metrology and inspection applications** [13426-101]
- 13426 2T **Novel 2D high-NA EUV pattern fidelity monitoring** [13426-103]
- 13426 2U **Shape-induced overlay for wafer-to-wafer hybrid bonding** [13426-104]
- 13426 2V **Compensation of lens aberration induced overlay by computational metrology** [13426-105]
- 13426 2X **Machine learning-based SEM images contour extraction data augmentation** [13426-107]
- 13426 2Y **Revolutionizing 3D defect analysis with advanced DualBeam (FIB/SEM)** [13426-108]
- 13426 2Z **Ultrafast AFM metrology for hybrid bonding applications** [13426-109]
- 13426 30 **Overcoming challenges raised by wafer load grid overlay fingerprints and correction per exposure management** [13426-110]
- 13426 31 **A comprehensive cross-layer overlay prediction method with reticle heating for enhanced process optimization** [13426-111]
- 13426 32 **AI-powered end-to-end product lifecycle: UX-centric human-in-the-loop system boosting reviewer productivity by 82% and accelerating decision-making via real-time anomaly detection and data refinement with GPU-accelerated computer vision, edge computing, and scalable cloud** [13426-112]
- 13426 33 **Development of mix-and-match overlay for multiple metrology platforms utilization by using the cross-layer overlay simulation method** [13426-113]
- 13426 34 **Overlay and wafer stress control in semiconductor manufacturing** [13426-114]
- 13426 35 **ASR adoption as a holistic monitor solution in DRAM technology** [13426-115]
- 13426 36 **Improving overlay accuracy through exposure correction using overlay prediction** [13426-116]
- 13426 37 **AFM metrology for 3D high aspect ratio semiconductor structures** [13426-117]
- 13426 38 **Surface charge mitigation in CD-SEM imaging and measurement of backside power delivery layers** [13426-118]
- 13426 39 **A holistic lithography approach to wafer edge overlay control** [13426-120]

- 13426 3A **Optical solution for potential EPE improvement by simultaneous in-die overlay and tilt measurements in DRAM HVM** [13426-121]
- 13426 3B **Quantitative metrology for anti-spacer patterning process development** [13426-122]
- 13426 3C **Process sensitivity analysis for EPE optimization of MP18 SALELE BEOL patterning** [13426-123]
- 13426 3E **Enhancing phase reconstruction fidelity via reflective Fourier ptychographic microscopy** [13426-125]
- 13426 3F **EUV ptychographic imaging for high-fidelity actinic inspection of periodic mask patterns with EUV ptychography microscope** [13426-126]
- 13426 3G **Inline evaluation of MOS capacitor properties using SEM transient signals** [13426-127]
- 13426 3H **A ViT-based approach for enhanced defect classification in nano-ridge engineering using multi-resolution images** [13426-128]
- 13426 3I **A study of CD-SAXS within-spot uniformity with mass CDSEM and 3D tomography** [13426-129]
- 13426 3J **Towards robust defect inspection in advanced node semiconductors via continual learning** [13426-130]
- 13426 3K **High-throughput gross anomaly detection from wafer image data utilizing computer vision and statistical feature extraction on symmetrical polar zones** [13426-131]
- 13426 3L **Toward a robust approach to multivariate time series anomaly detection** [13426-132]
- 13426 3M **High-speed modulation of probe current using scanning electron microscope with photocathode technology** [13426-133]
- 13426 3N **Image quality measurement: a novel approach to control metrology uncertainty and process quality of in-line CDSEM** [13426-134]
- 13426 3O **Enhancing defect detection in semiconductor manufacturing through physics-based synthetic imaging for micro- and nano-scale structures** [13426-135]
- 13426 3P **Method for reducing false positives using pattern binning based on unsupervised learning** [13426-136]
- 13426 3Q **Machine learning-based 3D TSV metrology for advanced packaging** [13426-137]
- 13426 3S **Investigation of lateral etch impact to the segmented alignment marks** [13426-139]
- 13426 3T **An out-of-focus blur removal technique for high-throughput overlay measurement** [13426-140]

- 13426 3U **Performance evaluation of transparent materials for EUV lithography [13426-141]**
- 13426 3W **Process window analysis using dual layer overlap area between metal via pair [13426-143]**
- 13426 3X **Characterization of pattern fidelity evaluation using sine wave patterns in electron multi-beam writing [13426-144]**
- 13426 3Y **Dual beam-based ultra-fast process control technology on high aspect ratio memory devices [13426-145]**
- 13426 3Z **Advances in machine learning and signal processing enabling expansion of after-etch metrology applications [13426-146]**
- 13426 40 **Optimizing electron emitter module geometry for improved lifetime through test-particle Monte Carlo (TPMC) simulation [13426-147]**
- 13426 41 **An improved ridge extraction algorithm for the development of lithographic masks [13426-148]**
- 13426 42 **Multi-electron beam inspection application in memory fab [13426-150]**
- 13426 43 **Particle (de-)charging in low pressure afterglow plasma for contamination control: a comparative study between conducting and non-conducting particles [13426-151]**
- 13426 45 **Advanced metrics for high-precision PCB inspection using 3D x-ray reconstruction [13426-197]**
- 13426 46 **Preserving fine details in PCB x-ray imaging: a patch-based data augmentation method for improved segmentation and detection [13426-200]**
- 13426 47 **SegPCBX: redefining automated PCB inspection with a novel PCB x-ray dataset for component analysis [13426-201]**
- 13426 49 **Advancing AI-driven computer vision and image segmentation via pattern recognition, GPU-accelerated unsupervised clustering, and edge AI for HPC-scalable big data processing: 85% efficiency gains [13426-205]**
- 13426 4A **Responsible defect detection with probabilistic contrastive counterfactuals [13426-206]**
- 13426 4C **X-ADAPT: AI-driven design-based strategy to address x-ray compatibility challenges in advanced packaging metrology [13426-209]**
- 13426 4D **Towards zero defects: machine learning-driven solder bump reliability in semiconductor packaging [13426-211]**